# imall

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BBY58...

# Silicon Tuning Diodes

- Excellent linearity
- High Q hyperabrupt tuning diode
- Low series resistance
- Designed for low tuning voltage operation for VCO's in mobile communications equipment
- For low frequency control elements such as TCXOs and VCXOs
- Very low capacitance spread
- Pb-free (RoHS compliant) package<sup>1)</sup>
- Qualified according AEC Q101



BBY58-05W

BBY58-02L/V BBY58-02W BBY58-03W

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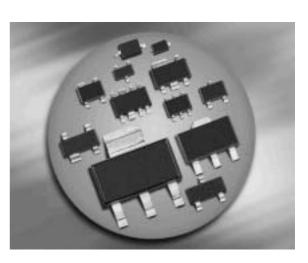
**BBY58-06W** 

Туре	Package	Configuration	<b>L</b> <sub>S</sub> (nH)	Marking
BBY58-02L	TSLP-2-1	single, leadless	0.4	88
BBY58-02V	SC79	single	0.6	8
BBY58-02W	SCD80	single	0.6	88
BBY58-03W	SOD323	single	0.6	8 yel.
BBY58-05W	SOT323	common cathode	1.4	B5s
BBY58-06W	SOT323	common anode	1.4	B6s

### **Maximum Ratings** at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V <sub>R</sub>	10	V
Forward current	/ <sub>F</sub>	20	mA
Operating temperature range	T <sub>op</sub>	-55 150	°C
Storage temperature	T <sub>stg</sub>	-55 150	

<sup>1</sup>Pb-containing package may be available upon special request





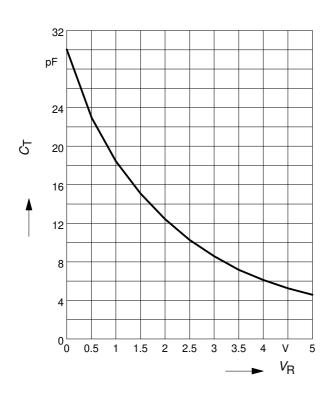
Parameter	Symbol		Unit			
		min.	typ.	max.		
DC Characteristics	·	·				
Reverse current	I <sub>R</sub>				nA	
$V_{R} = 8 V$		-	-	10		
$V_{\rm R} = 8 \text{ V}, \ T_{\rm A} = 85 \text{ °C}$		-	-	100		
AC Characteristics						
Diode capacitance	CT				pF	
$V_{R} = 1 V, f = 1 MHz$		17.5	18.3	19.3		
$V_{\rm R} = 2  {\rm V},  f = 1  {\rm MHz}$		11.4	12.35	13.3		
$V_{\rm R} = 3  {\rm V},  f = 1  {\rm MHz}$		7.8	8.6	9.3		
$V_{\rm R}$ = 4 V, f = 1 MHz		5.5	6	6.6		
$V_{\rm R} = 6  {\rm V},  f = 1  {\rm MHz}$		3.8	4.7	5.5		
Capacitance ratio	$C_{T1}/C_{T3}$	1.9	2.15	2.4	-	
$V_{\rm R} = 1  \text{V},  V_{\rm R} = 3  \text{V},  f = 1  \text{MHz}$						
Capacitance ratio	$C_{T1}/C_{T4}$	2.7	3.05	3.5		
$V_{\rm R} = 1  {\rm V},  V_{\rm R} = 4  {\rm V},  f = 1  {\rm MHz}$						
Capacitance ratio	$C_{T4}/C_{T6}$	1.15	1.3	1.45	Ţ	
$V_{\rm R} = 4 \text{ V}, V_{\rm R} = 6 \text{ V}, f = 1 \text{ MHz}$						
Series resistance	r <sub>S</sub>				Ω	
<i>V</i> <sub>R</sub> = 1 V, <i>f</i> = 470 MHz, BBY58-02L, -07L4		-	0.3	-		
$V_{\rm R}$ = 1 V, f = 470 MHz, all other		-	0.25	-		

# **Electrical Characteristics** at $T_A = 25^{\circ}$ C, unless otherwise specified

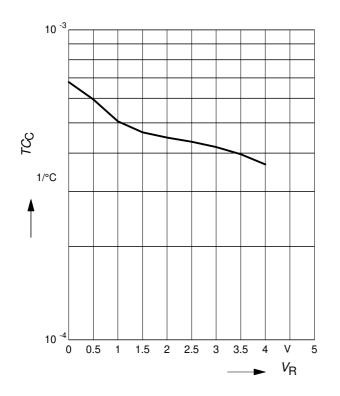


# Diode capacitance $C_{T} = f(V_{R})$

f = 1 MHz

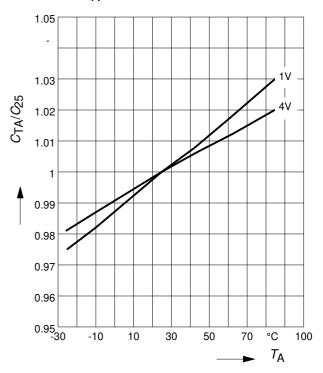


# Temperature coefficient of the diode capacitance $T_{CC} = f (V_R)$

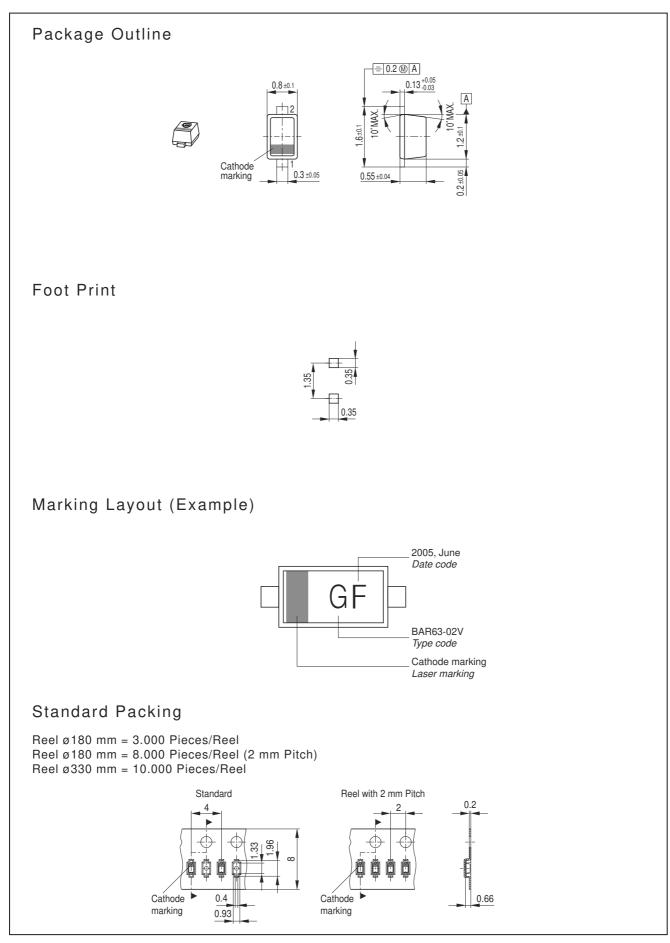


#### Normalized diode capacitance

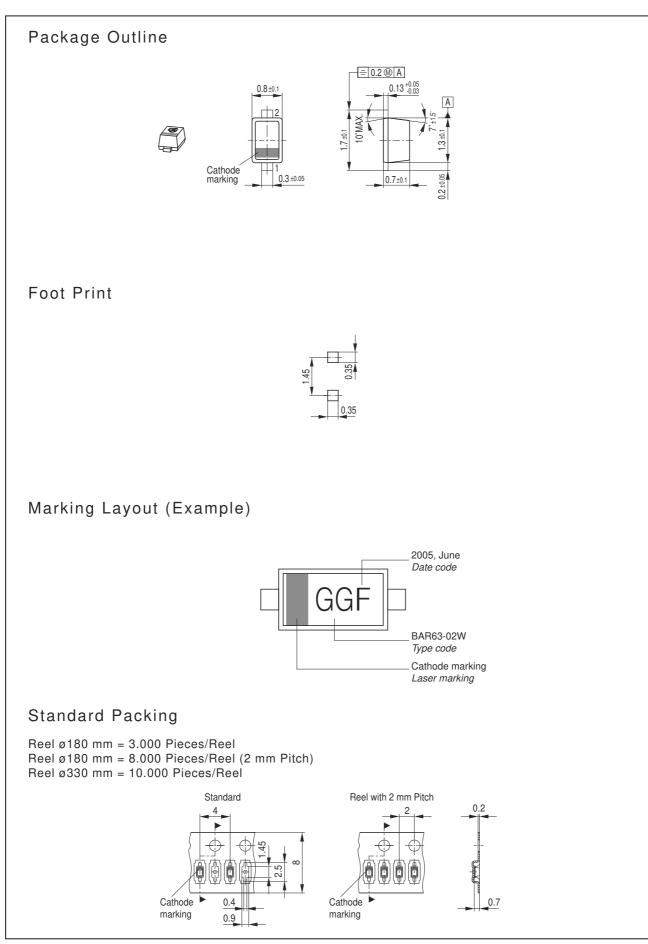
 $C_{(TA)}/C_{(25^{\circ}C)} = f(T_A)$ f = 1MHz,  $V_R$  = Parameter













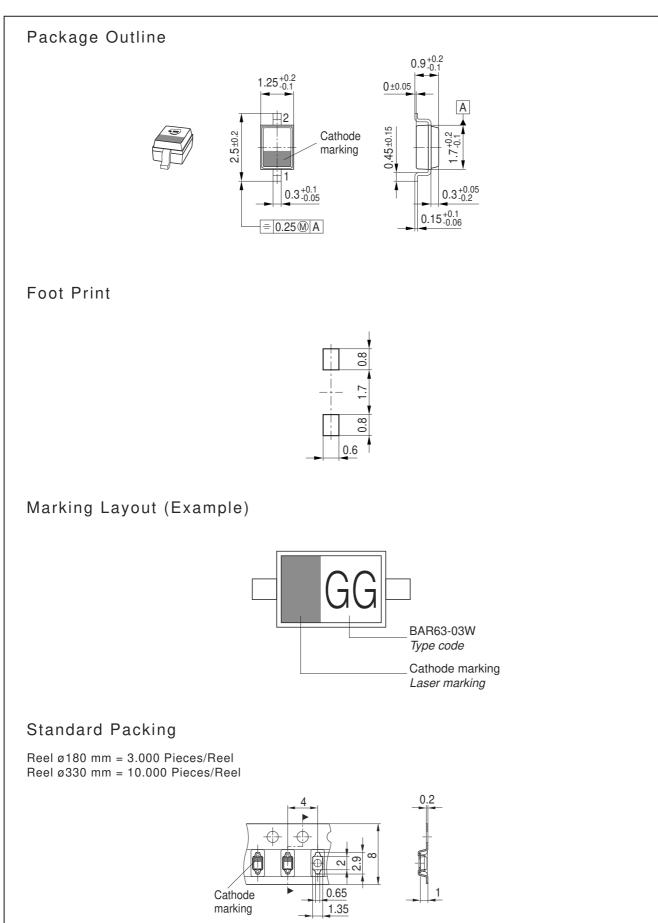
# Date Code marking for discrete packages with one digit (SCD80, SC79, SC75<sup>1)</sup>) CES-Code

Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	а	р	А	Р	а	р	А	Р	а	р	А	Р
02	b	q	В	Q	b	q	В	Q	b	q	В	Q
03	С	r	С	R	С	r	С	R	С	r	С	R
04	d	S	D	S	d	S	D	S	d	S	D	S
05	е	t	E	Т	е	t	E	Т	е	t	E	Т
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	V	G	V	g	V	G	V	g	V	G	V
08	h	Х	Н	Х	h	Х	Н	Х	h	Х	Н	Х
09	j	у	J	Y	j	у	J	Y	j	у	J	Y
10	k	Z	K	Z	k	Z	K	Z	k	Z	K	Z
11	I	2	L	4	I	2	L	4		2	L	4
12	n	3	Ν	5	n	3	Ν	5	n	3	Ν	5

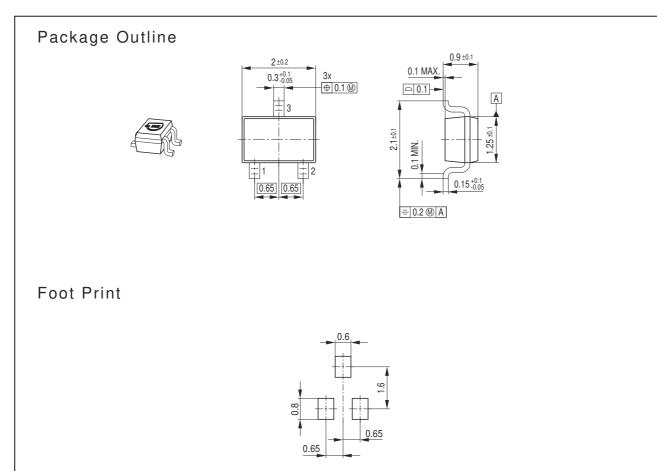
1) New Marking Layout for SC75, implemented at October 2005.

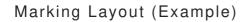
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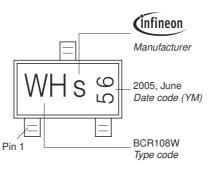






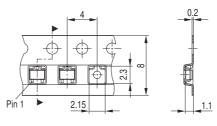




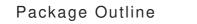


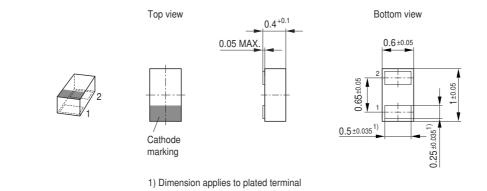
### Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel Reel ø330 mm = 10.000 Pieces/Reel



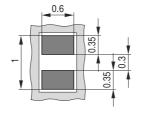




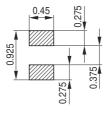


# Foot Print

For board assembly information please refer to Infineon website "Packages"

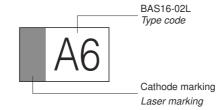


Copper Solder mask



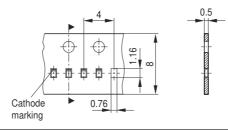
Stencil apertures

# Marking Layout (Example)



## Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel Reel ø330 mm = 50.000 Pieces/Reel (optional)





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